

Amendment to the Abstract:

The Abstract has been amended. A revised Abstract is attached.

ABSTRACT

~~According to the present invention,~~ A mask film (2a), where squeegee cleaning part (6) has been formed at a predetermined position, and another mask film (2b) are attached to both sides of a substrate. ~~Through-hole~~ A through-hole (3) is formed by using a laser, and conductive paste (4) is filled into the through-hole (3) by using a squeezing method. As discussed above, a paste-residue can be prevented on the through-hole (3), so that a circuit board having high quality of connection can be obtained.